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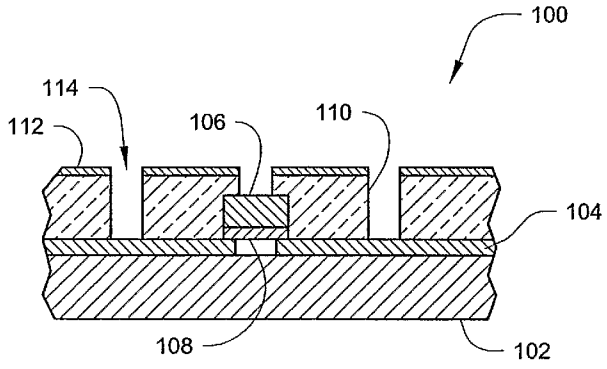
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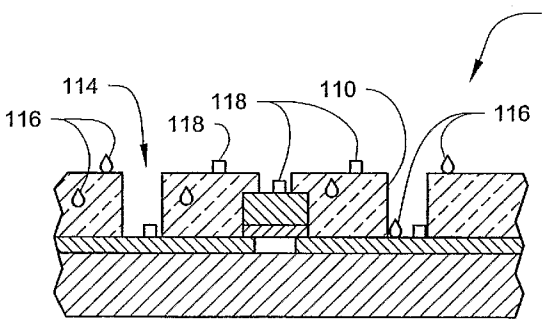
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(54) **Title:** POLAR FLUID REMOVAL FROM SURFACES USING SUPERCRITICAL FLUIDS



A



B

(57) **Abstract:** A method for removing polar fluids from the surface of a substrate using a supercritical fluid is described. Substrates that may be cleaned include microelectronic devices such as integrated circuits, micro-electro mechanical devices, and optoelectronic devices. The surfaces of these devices may include foamed polymers, such as those used as dielectric material. Supercritical fluids useful for removal of polar fluids generally include an oxygen-containing organic compound in the supercritical state. The removal of polar fluids using supercritical fluids may be supplemented by other cleaning methods using supercritical fluids to remove particulate matter from the surface of the substrate.

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